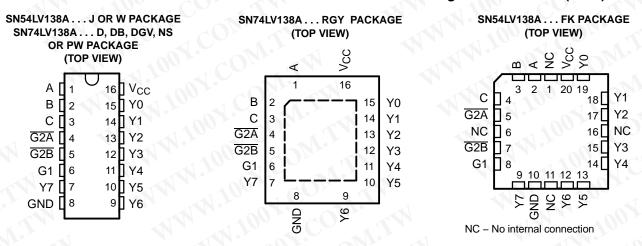
# SN54LV138A, SN74LV138A 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

SCLS395L-APRIL 1998-REVISED AUGUST 2005

#### **FEATURES**

- 2-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 9.5 ns at 5 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



#### **DESCRIPTION/ORDERING INFORMATION**

The 'LV138A devices are 3-line to 8-line decoders/demultiplexers designed for 2-V to 5.5-V V<sub>CC</sub> operation.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PAG	CKAGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
10	QFN – RGY	Reel of 1000	SN74LV138ARGYR	LV138A
	SOIC - D	Tube of 40	SN74LV138AD	11/4204
	SOIC – D	Reel of 2500	SN74LV138ADR	LV138A
	SOP - NS	Reel of 2000	SN74LV138ANSR	74LV138A
–40°C to 85°C	SSOP - DB	Reel of 2000	SN74LV138ADBR	LV138A
		Tube of 90	SN74LV138APW	
	TSSOP - PW	Reel of 2000	SN74LV138APWR	LV138A
	1 CV (3)	Reel of 250	SN74LV138APWT	
	TVSOP - DGV	Reel of 2000	SN74LV138ADGVR	LV138A
	CDIP – J	Tube of 25	SNJ54LV138AJ	SNJ54LV138AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV138AW	SNJ54LV138AW
	LCCC - FK	Tube of 55	SNJ54LV138AFK	SNJ54LV138AFK

 Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SCLS395L-APRIL 1998-REVISED AUGUST 2005





# **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

These devices are designed for high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The conditions at the binary-select inputs (A, B, C) and the three enable inputs (G1,  $\overline{G2A}$ ,  $\overline{G2B}$ ) select one of eight output lines. The two active-low ( $\overline{G2A}$ ,  $\overline{G2B}$ ) and one active-high (G1) enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

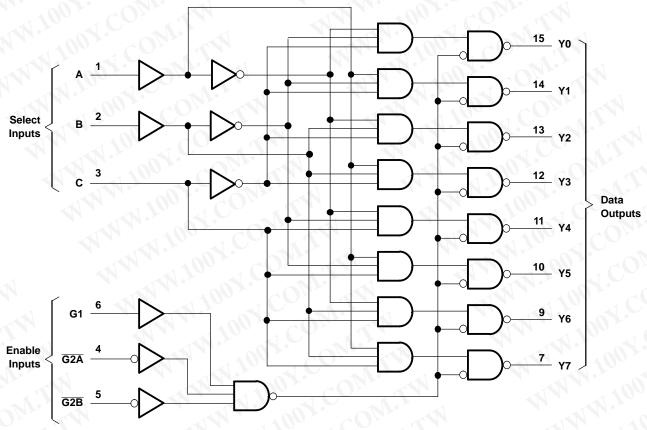
These devices are fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

#### **FUNCTION TABLE**

ENA	BLE IN	PUTS	SEL	ECT INF	PUTS		-1		OUT	PUTS		7	41
G1	G2A	G2B	C	В	A	Y0	Y1	Y20	Y3	Y4	Y5	Y6	Y7
X	H	X	X	X	X	Н	Н	Н	Н	Н	Н	Н	Н
Χ	X	Н	X	Χ	X	Н	Н	Н	Н	Н	Н	H,	Н
L	Χ	X	Χ	X	X	H	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	_1LC	L	Н	Н	Н	Н	H	Н	Н
Н	L	L	L	L	Н	Н	L	Н	Н	Н	Н	H	Н
Н	L	L	L	Н	L	Н	Н	L	ДH	Н	Н	Н	Н
Н	L	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
Н	L	L	Н	L	L	H	Н	Н	Н	L	Н	Н	H
Н	L	L	Н	L	Н	Н	H	Н	Н	Н	L	Н	Н
H	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
Н	L	L	Н	Н	Н	Н	Н	Ĥ	Н	Н	Н	Н	L

SCLS395L-APRIL 1998-REVISED AUGUST 2005

# LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, RGY, and W packages.

力 材 料 886-3-5753170 胜特力电子(深圳) 86-755-83298787 Http://www.100v.com.tw



SCLS395L-APRIL 1998-REVISED AUGUST 2005

# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

	100 (0)	100	MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	1111.	-0.5	7	V
VI	Input voltage range <sup>(2)</sup>	1100	-0.5	7	V
Vo	Voltage range applied to any output in the high	gh-impedance or power-off state <sup>(2)</sup>	-0.5	7	V
Vo	Output voltage range <sup>(2)(3)</sup>	11 10	-0.5	$V_{CC} + 0.5$	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0	00, 40	-20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current	$V_O = 0$ to $V_{CC}$	100	±25	mA
	Continuous current through V <sub>CC</sub> or GND			±50	mA
	1100	D package <sup>(4)</sup>	11100	73	
		DB package <sup>(4)</sup>	14.	82	
0	P. L. Silver and A. C.	DGV package <sup>(4)</sup>		120	0000
$\theta_{JA}$	Package thermal impedance	NS package <sup>(4)</sup>	00	64	°C/W
		PW package <sup>(4)</sup>		108	
		RGY package <sup>(5)</sup>		39	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> (3) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

This value is limited to 5.5 V maximum.

The package thermal impedance is calculated in accordance with JESD 51-7

The package thermal impedance is calculated in accordance with JESD 51-5.

SCLS395L-APRIL 1998-REVISED AUGUST 2005

# Recommended Operating Conditions<sup>(1)</sup>

			SN54LV1	38A <sup>(2)</sup>	SN74L	.V138A	
			MIN	MAX	MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	5.5	2	5.5	V
	1100 1 CO.	V <sub>CC</sub> = 2 V	1.5	-1 C	1.5		
V	Lligh level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	$V_{CC} \times 0.7$	0.3.	$V_{CC} \times 0.7$		V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
	11/1/1/10/1/1	V <sub>CC</sub> = 4.5 V to 5.5 V	$V_{CC} \times 0.7$	$^{\prime}$ $^{\prime}$ $^{\prime}$	$V_{CC} \times 0.7$		N
		$V_{CC} = 2 V$		0.5		0.5	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
۷IL	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$	<b>J</b>	$V_{\text{CC}} \times 0.3$	
$V_{I}$	Input voltage	7. 011.	0	5.5	0	5.5	V
Vo	Output voltage		0	$V_{CC}$	0	V <sub>CC</sub>	V
		$V_{CC} = 2 V$		-50	00	-50	μΑ
ıs 1	High lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V to 3.6 V		-6	1	-6	mA
		V <sub>CC</sub> = 4.5 V to 5.5 V		-12		-12	
		$V_{CC} = 2 V$	1	50	W .	50	μΑ
• ′	Low-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	41	2		2	
l <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V to 3.6 V		6		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	M	12		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200	11/4	200	
$\Delta t/\Delta v$	Input transition rise or fall rate	V <sub>CC</sub> = 3 V to 3.6 V		100	_1	100	ns/V
		V <sub>CC</sub> = 4.5 V to 5.5 V	41	20		20	7
TA	Operating free-air temperature	100 00	-55	125	-40	85	°C

All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004. Product Preview

# **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPITIONS		SN54LV138A <sup>(1)</sup>	SN74LV138A	LINUT
PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN TYP MAX	MIN TYP MAX	UNIT
100	$I_{OH} = -50  \mu A$	2 V to 5.5 V	V <sub>CC</sub> - 0.1	V <sub>CC</sub> - 0.1	
	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	V
V <sub>OH</sub>	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8	3.8	
100	I <sub>OL</sub> = 50 μA	2 V to 5.5 V	0.1	0.1	
	I <sub>OL</sub> = 2 mA	2.3 V	0.4	0.4	V
V <sub>OL</sub>	I <sub>OL</sub> = 6 mA	3 V	0.44	0.44	V
	I <sub>OL</sub> = 12 mA	4.5 V	0.55	0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ
I <sub>CC</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ
I <sub>off</sub>	$V_I$ or $V_O = 0$ to 5.5 V	0	5	5	μΑ
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	2.1	2.1	pF

(1) Product Preview

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw



SCLS395L-APRIL 1998-REVISED AUGUST 2005

# **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CC}$  = 2.5 V  $\pm$  0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD		$T_A = 25^{\circ}$		SN54LV1	38A <sup>(1)</sup>	SN74L	.V138A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
	A, B, or C				11.7(2)	17.6 <sup>(2)</sup>	1 (2)	21(2)	1	21	
t <sub>pd</sub>	G1	Υ	$C_{L} = 15 \text{ pF}$		12.3 <sup>(2)</sup>	19.2 <sup>(2)</sup>	1 (2)	22(2)	1	22	ns
	G2A or G2B			4	11.4 <sup>(2)</sup>	18.2 <sup>(2)</sup>	1 <sup>(2)</sup>	21 (2)	1	21	
	A, B, or C	90 J			14.9	21.4	1001	25	1	25	
t <sub>pd</sub>	G1	Υ	$C_L = 50 pF$		15.7	22.6	1	26	1	26	ns
	G2A or G2B	$CO_{\lambda}$			14.8	22	1	25	(1)	25	

<sup>(1)</sup> Product Preview

# **Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CC}$  = 3.3 V  $\pm$  0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD		T <sub>A</sub> = 25°	С	SN54LV	138A <sup>(1)</sup>	SN74L	V138A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A, B, or C				8.1 <sup>(2)</sup>	11.4 <sup>(2)</sup>	1 (2)	13.5 <sup>(2)</sup>	1	13.5	
t <sub>pd</sub>	G1	Υ	$C_{L} = 15 \text{ pF}$		8.4(2)	12.8(2)	1 (2)	15 <sup>(2)</sup>	1	15	ns
	G2A or G2B		" UO J. " C	1	7.8(2)	11.4 <sup>(2)</sup>	1 (2)	13.5 <sup>(2)</sup>	1	13.5	
	A, B, or C				10.3	15.8	1	18	1	18	7
t <sub>pd</sub>	G1	Υ	$C_L = 50 \text{ pF}$	O.E.	10.6	16.3	1	18.5	1	18.5	ns
	G2A or G2B		N. Y		10	14.9	1	17	1	17	

<sup>1)</sup> Product Preview

# Switching Characteristics

over recommended operating free-air temperature range,  $V_{CC}$  = 5 V  $\pm$  0.5 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD		Γ <sub>A</sub> = 25°C	) ×	SN54LV	138A <sup>(1)</sup>	SN74L	V138A	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
100	A, B, or C	,		120	5.6 <sup>(2)</sup>	8.1 (2)	1 (2)	9.5 <sup>(2)</sup>	1	9.5	
$t_{pd}$	G1	Y	$C_{L} = 15 \text{ pF}$		5.7 <sup>(2)</sup>	8.1 <sup>(2)</sup>	1 (2)	9.5 <sup>(2)</sup>	1	9.5	ns
70	G2A or G2B	-1			5.4 <sup>(2)</sup>	8.1 (2)	1 (2)	9.5(2)	1	9.5	
100	A, B, or C				7	10.1	1	11.5	1	11.5	
t <sub>pd</sub>	G1	Υ	$C_{L} = 50 \text{ pF}$		7.1	10.1	1	11.5	1	11.5	ns
100	G2A or G2B				6.8	10.1		11.5	1	11.5	

<sup>(1)</sup> Product Preview

# **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	TYP	UNIT
^	Daving discharge annuals	C 50 75 6 40 MHz	3.3 V	16.8	
$C_{pd}$	Power dissipation capacitance	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	5 V	19.1	pF

<sup>(2)</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested

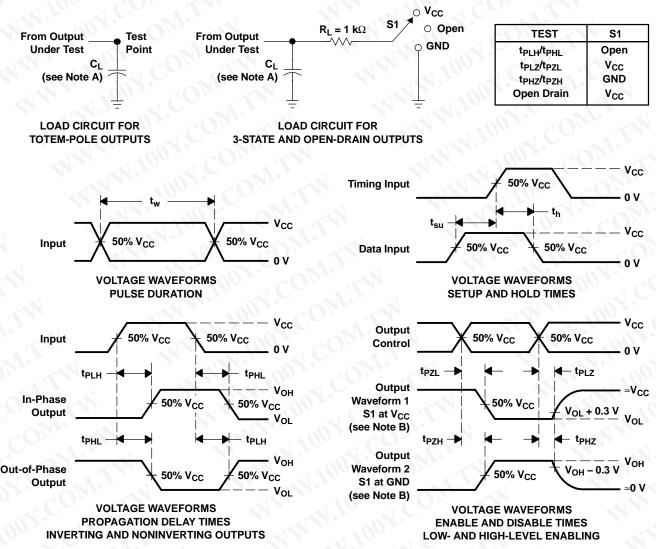
<sup>(2)</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

<sup>(2)</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.



SCLS395L-APRIL 1998-REVISED AUGUST 2005

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq$  3 ns,  $t_f \leq$  3 ns.
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PHL</sub> and t<sub>PLH</sub> are the same as t<sub>pd</sub>.
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Applications Amplifiers** amplifier.ti.com Audio www.ti.com/audio **Data Converters** dataconverter.ti.com Automotive www.ti.com/automotive DSF Broadband www.ti.com/broadband dsp.ti.com interface.ti.com **Digital Control** www.ti.com/digitalcontrol Interface Military logic.ti.com www.ti.com/military Logic Power Mgmt Optical Networking www.ti.com/opticalnetwor power.ti.com Microcontrollers microcontroller.ti.com Security www.ti.com/security Telephony Low Power www.ti.com/telephony www.ti.com/lpw Wireless Video & Imaging www.ti.com/video Wireless www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2007, Texas Instruments Incorporated







# **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV138AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADGVRG4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ANSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138APWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV138ARGYR	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LV138ARGYRG4	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
417	~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~							



# PACKAGE OPTION ADDENDUM

18-Sep-2008

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

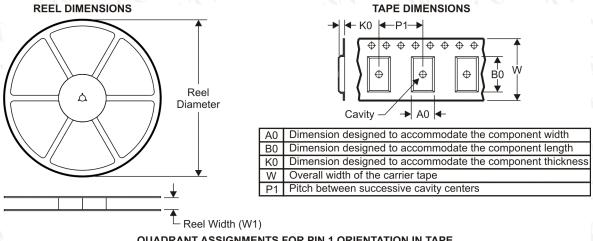
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



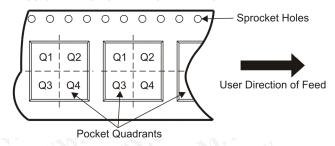
# PACKAGE MATERIALS INFORMATION

19-Mar-2008

#### TAPE AND REEL INFORMATION



#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



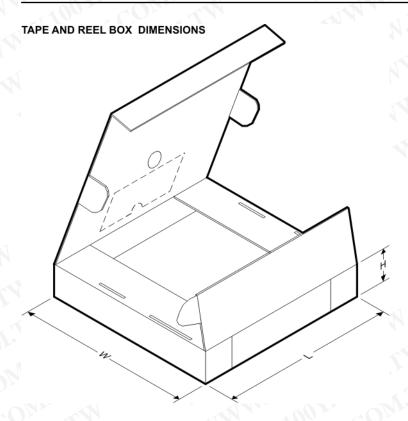
#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV138ADBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV138ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV138ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV138ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV138APWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV138ARGYR	QFN	RGY	16	1000	180.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

# PACKAGE MATERIALS INFORMATION



19-Mar-2008



WWW.100X.COM.TW

100X.COM.TW

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

WWW.100Y.COM.TW

TOON COM'LLA

TONY CONLT

#### \*All dimensions are nominal

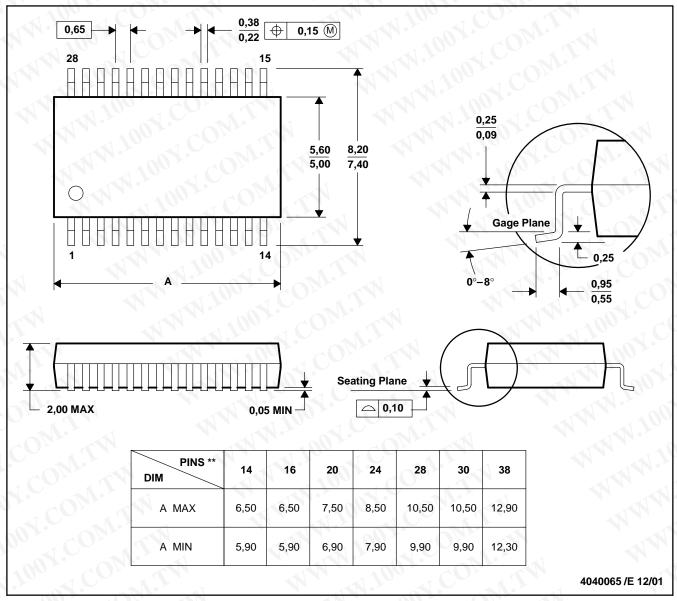
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm
SN74LV138ADBR	SSOP	DB	16	2000	346.0	346.0	33.0
SN74LV138ADGVR	TVSOP	DGV	16	2000	346.0	346.0	29.0
SN74LV138ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV138ANSR	so	NS	16	2000	346.0	346.0	33.0
SN74LV138APWR	TSSOP	PW	16	2000	346.0	346.0	29.0
SN74LV138ARGYR	QFN	RGY	16	1000	190.5	212.7	31.8

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

# DB (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

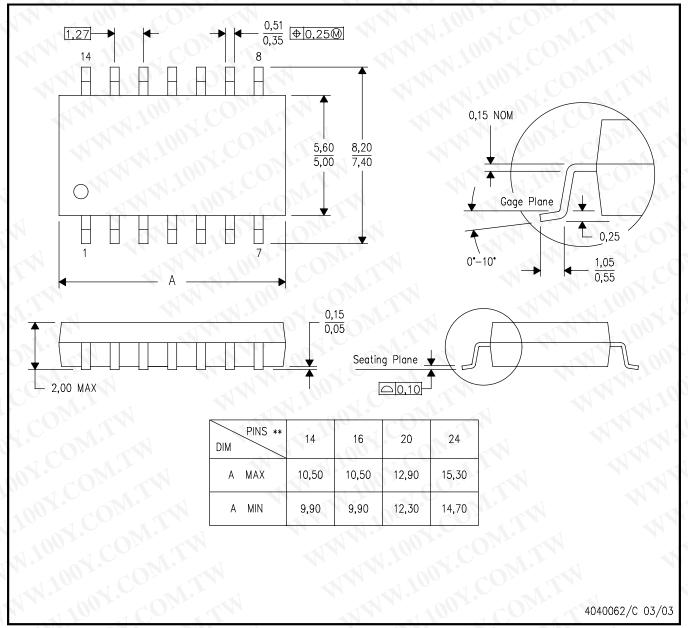
D. Falls within JEDEC MO-150

# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

### 14-PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

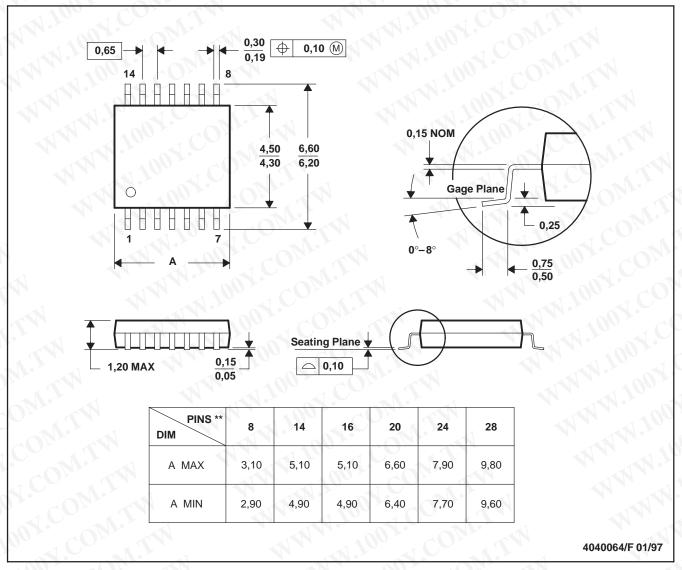


MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

# PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

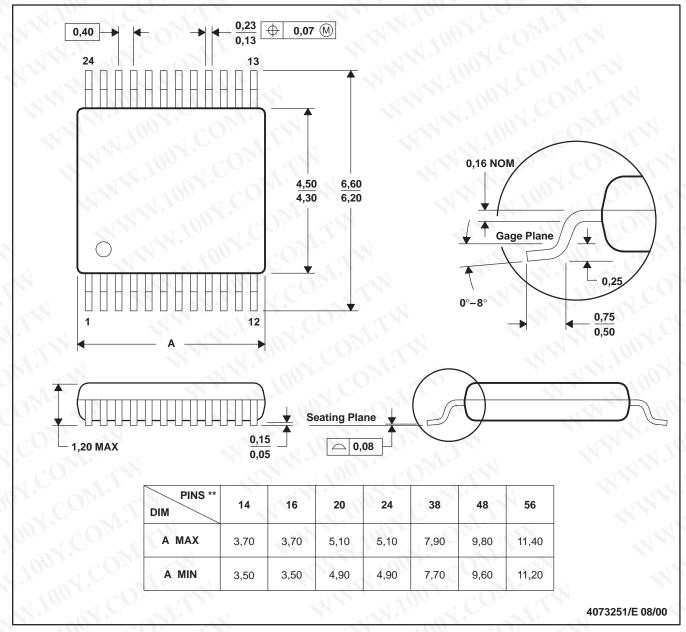
D. Falls within JEDEC MO-153

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

# DGV (R-PDSO-G\*\*)

#### 24 PINS SHOWN

#### PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

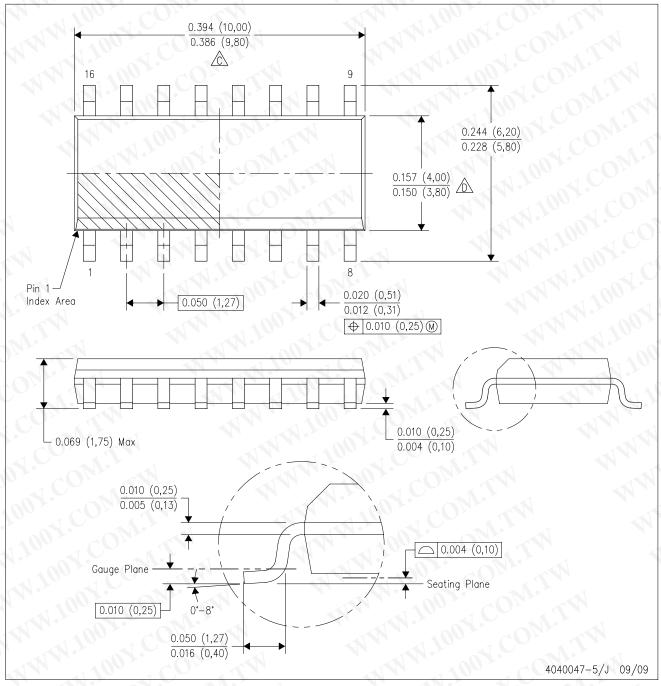
D. Falls within JEDEC: 24/48 Pins - MO-153

14/16/20/56 Pins - MO-194



# D (R-PDSO-G16)

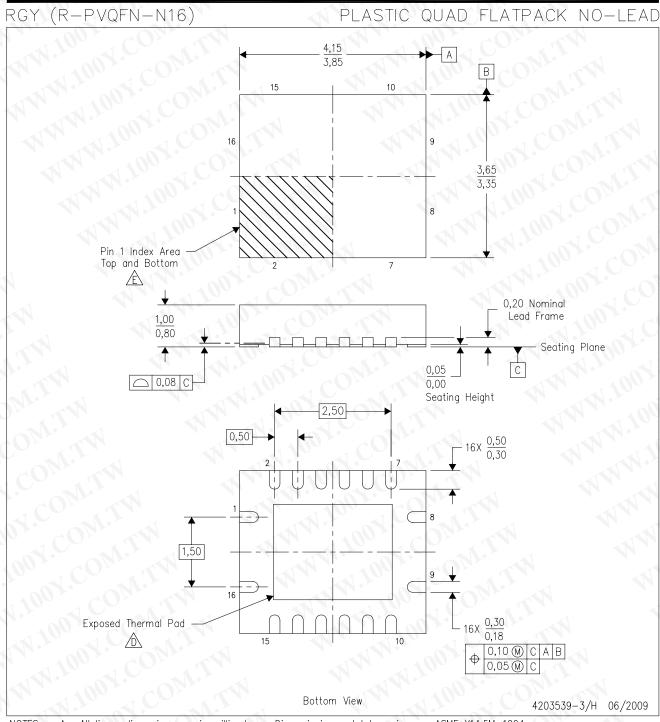
# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.

  See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BB.





# THERMAL PAD MECHANICAL DATA

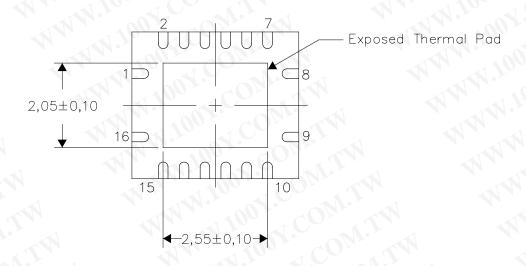
RGY (R-PVQFN-N16)

### THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No—Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

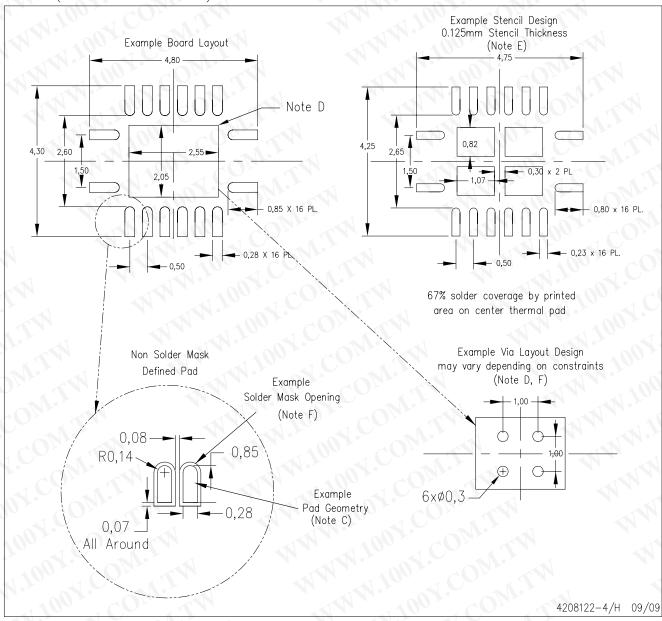


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGY (R-PVQFN-N16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <a href="https://www.ti.com">http://www.ti.com</a>.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

**Products Amplifiers** amplifier.ti.com **Data Converters** dataconverter.ti.com **DLP® Products** www.dlp.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com **RFID** www.ti-rfid.com www.ti.com/lprf RF/IF and ZigBee® Solutions

Applications Audio www.ti.com/audio Automotive www.ti.com/automotive Broadband www.ti.com/broadband Digital Control www.ti.com/digitalcontrol Medical www.ti.com/medical Military www.ti.com/military Optical Networking www.ti.com/opticalnetwork Security www.ti.com/security Telephony www.ti.com/telephony Video & Imaging www.ti.com/video Wireless www.ti.com/wirele

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated